

Please amend the application as follows:

**In the Claims:**

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a<sup>1</sup> 1. (amended) A multilayer composite attachment film for use in assembling semiconductor devices, comprising:

- an unpatterned metal foil having first and second surfaces; and
- an adhesive layer attached on each of said surfaces;

whereby said multilayer composite has an average modulus greater than the modulus of a polymerized encapsulation material.

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a<sup>2</sup> 14. (amended) The device according to Claim 12 further comprising a protective encapsulation, said encapsulation enclosing said active chip surface, said bonding wires, and portions of said first surface of said composite.

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Please cancel non-elected claims 18-21 without prejudice.

Please add the following new claims:

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a<sup>3</sup> 22. A semiconductor device comprising:

- a semiconductor chip having an active and a passive surface;
- a composite attachment film comprising a metal foil having first and second surfaces and an adhesive layer on each of said surfaces of said metal layer; said passive surface of said chip attached to said adhesive layer on said first surface of said metal foil; and
- a substrate; wherein said adhesive layer on said second surface of said metal foil is attached to said substrate.

23. The device of Claim 22, further comprising bonding wires attaching said active surface of said chip to said substrate.